



# CIRTEK ELECTRONICS CORPORATION

116 East Avenue, Phase V, SEZ Laguna Technopark  
Binan, Laguna, Philippines

## PRODUCT INFORMATION

Customer :

Device :

Device ID :

Die Size :

Wafer Material :

Package Type:

4L SOT-143

No. of Wires :

## MATERIAL INFORMATION

Leadframe :

A42 with spot Ag

Pad Size :

60X36 mils

Epoxy :

Gold Wire :

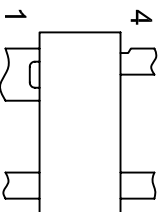
Molding Compound :

Lead Finish :

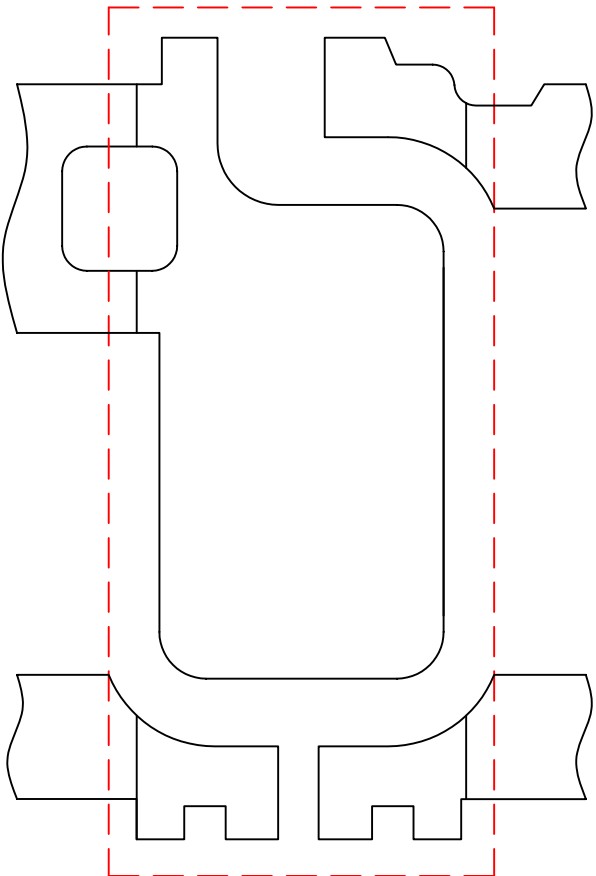
## MARKING INSTRUCTION

TOP :

BOTTOM :



BONDING DIAGRAM NO.



REF. BONDING DIAGRAM NO.

SCALE

not to scale

DRAWN BY:

REVIEWED BY:

REVISION NO.

APPROVALS

SPECIAL INSTRUCTION :

REV. #	DESCRIPTION	ECN #	DEPT	APPROVALS	DATE
			CUST		
			QSM		
			QC		
			MFG		